

## C0603C332K3GECTU

Aliases (C0603C332K3GEC7867)

ESD SMD Comm COG, Ceramic, 3300 pF, 10%, 25 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0603



Click [here](#) for the 3D model.

### Dimensions

Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
T	0.8mm +/-0.07mm
S	0.7mm MIN
B	0.35mm +/-0.15mm

### Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

### General Information

Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	3.7 mg
Shelf Life	78 Weeks
MSL	1

### Specifications

Capacitance	3300 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	25 VDC
ESD Level per AEC-Q200	16,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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